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## 一级代理商：

深圳市弗瑞鑫电子有限公司

地址：深圳市宝安区西乡大道302号金源商务大厦B座三楼

frxelec

Feature

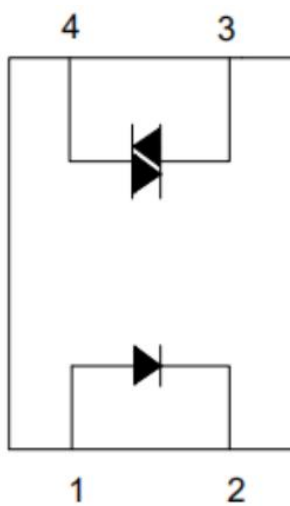


Decision

3. Application Range

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- 
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4. Functional Diagram



- 1. Anode
- 2. Cathode
- 3. Main terminal
- 4. Main terminal

5. Abol e Ma im m Ra ing (Ta=25 )

| Pa ame e |  | S mbol | Ra ed Val e | Uni |
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|          |  |        |             |     |

6. Elec tical O ical Cha ac e i ic a Ta=25 C

| Pa ame e |  | S mbol | Min | T .* | Ma | Uni | Condi ion |
|----------|--|--------|-----|------|----|-----|-----------|
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**7. O de Info ma ion**

**Pa N mbe**

**OR-M302X(L)-W-Y-Z**

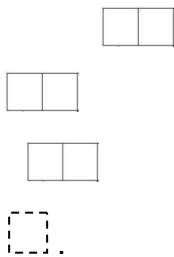
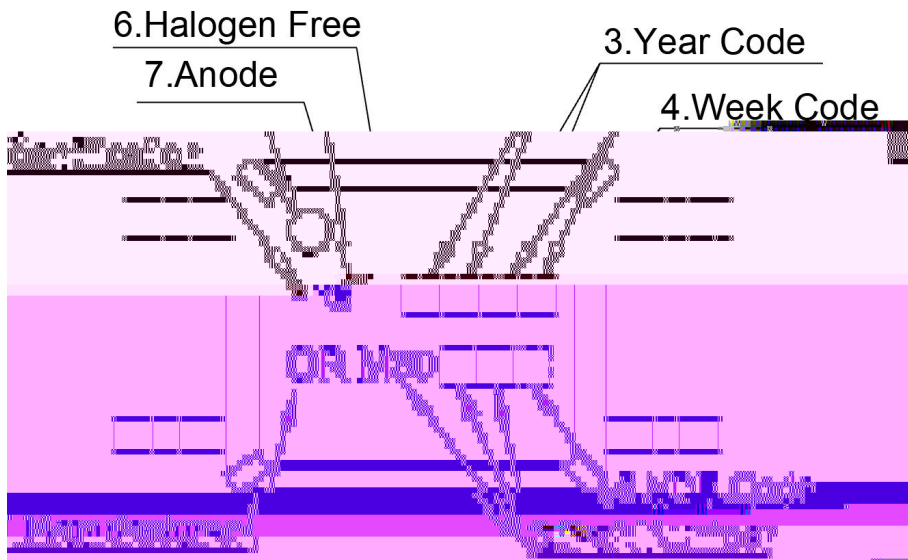
**OR-M305X(L)-W-Y-Z**

**o OR-M307X(L)-W-Y-Z**

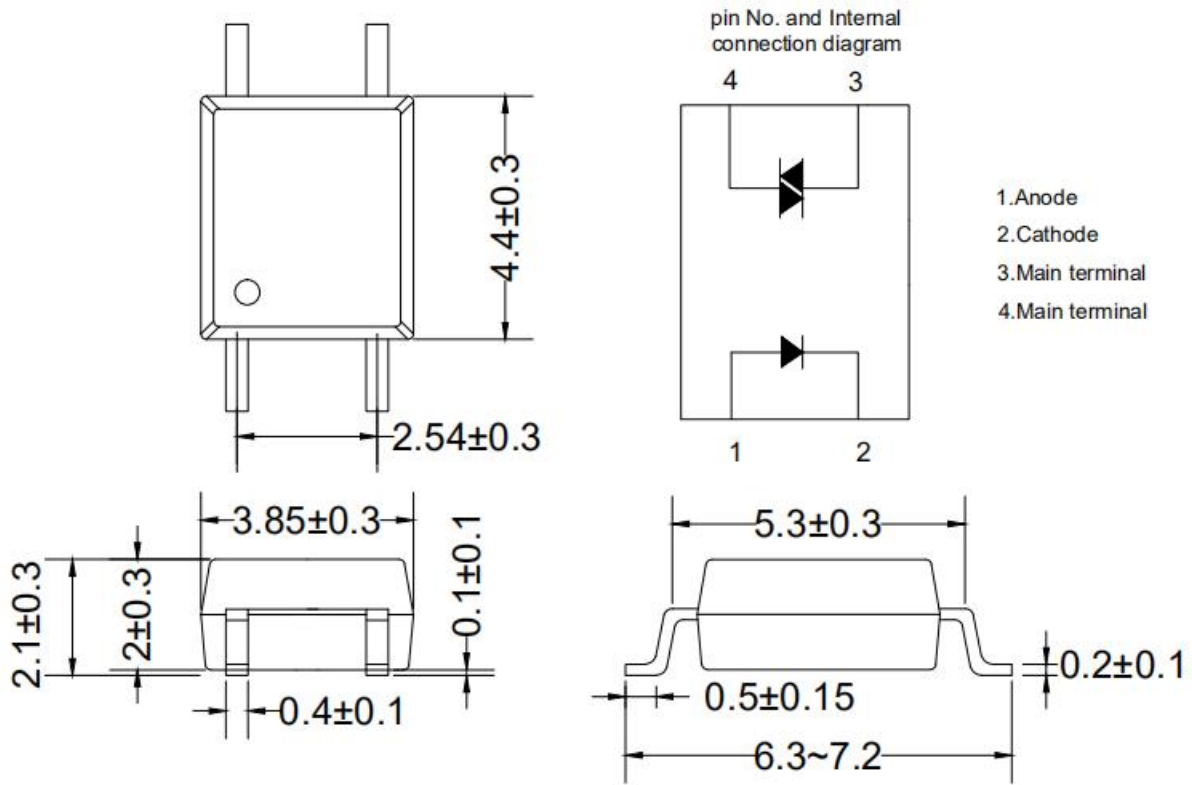
**No e**

| <b>O ion</b> | <b>De c i ion</b> | <b>Packing an i</b> |
|--------------|-------------------|---------------------|
|              |                   |                     |
|              |                   |                     |

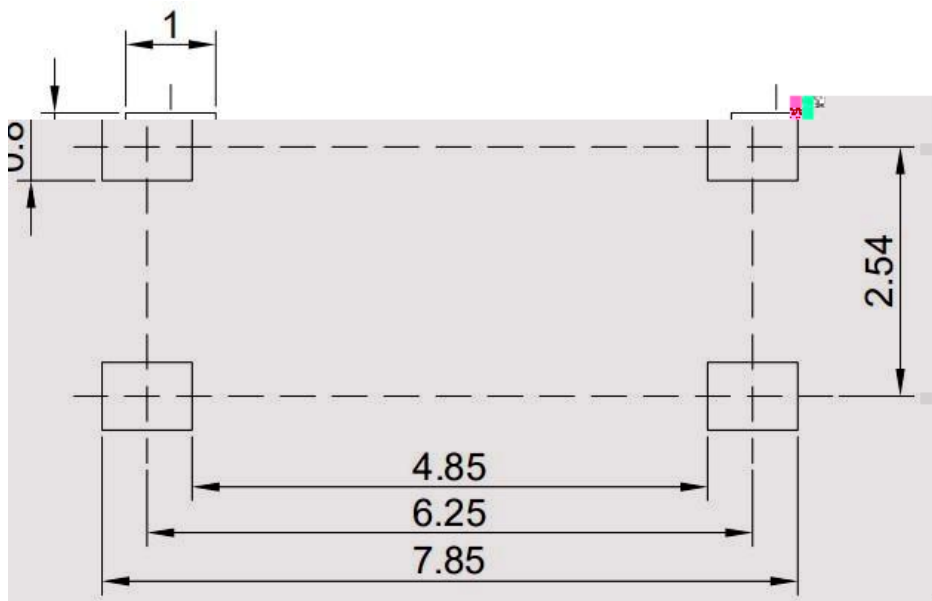
## 8. Naming Rule



### 9. Package Dimension

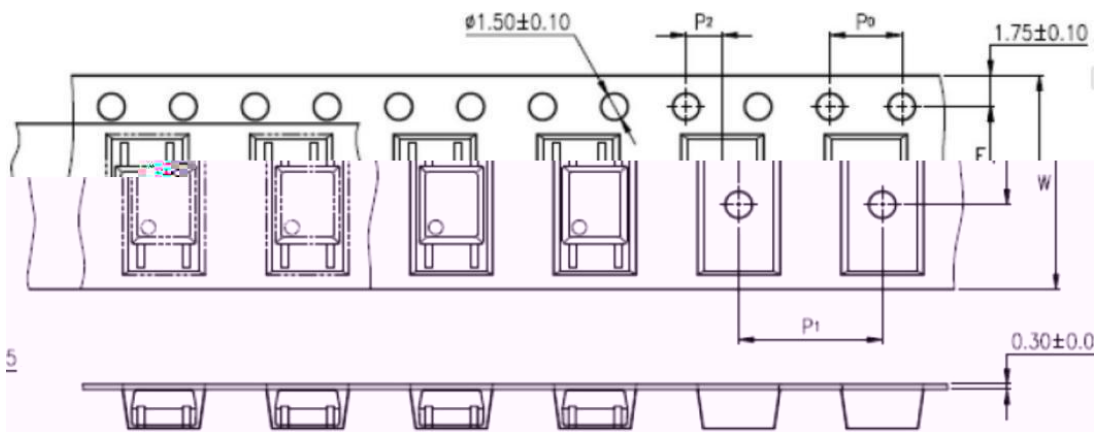
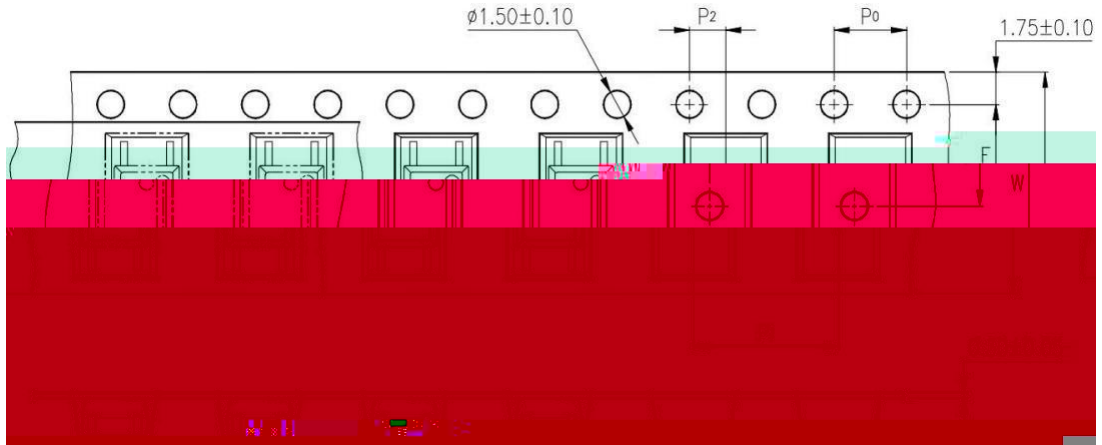


### 10. Recommended Foot Print Pattern (Mount Pad)



ni mm

### 11. Ta ing Dimen ion




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## 12. Package Dimension

| Packing Information |  |
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**ORIENT**  
ShenZhen Orient  
Components Co.,LTD

Material Code : 120PCXXXXXX

||||| P/N : OR-XXXXXX |||||

||||| Lot No. : XXXXXX-XXXX-TX-X |||||

||||| D/C : XXXX |||||

||||| Qty : XXXX PCS |||||

内箱码


外箱码

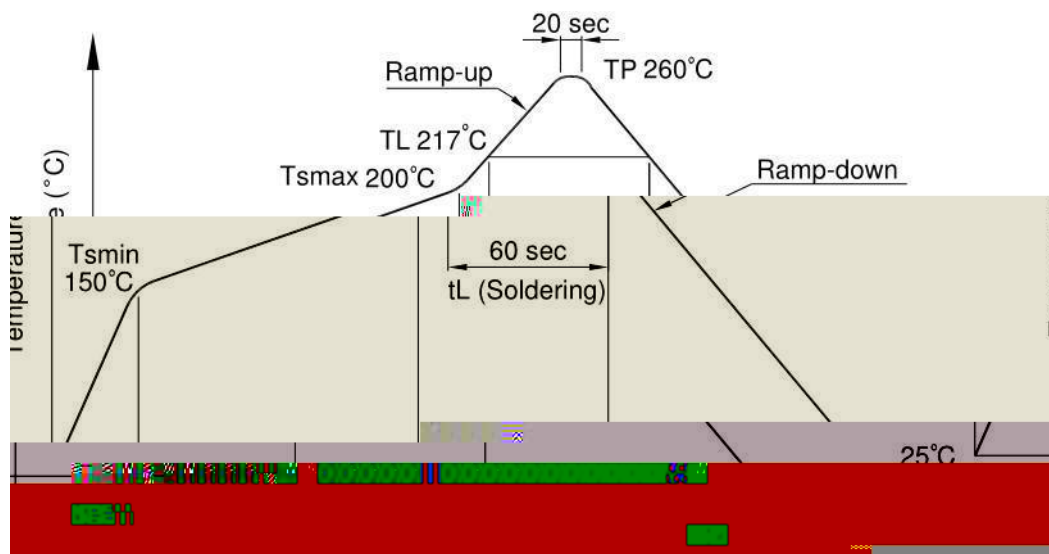
“XXXXXXXXXXXXXXXXXX” (一体机序列码)

**Made in China**

No e

### 13. Temperature Profile Of Soldering

| Profile Item  | Condition |
|---|-----------|
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|-------------|------------|
| Temperature | 380+0/-5°C |
| Time        | 3 sec max  |

## 14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

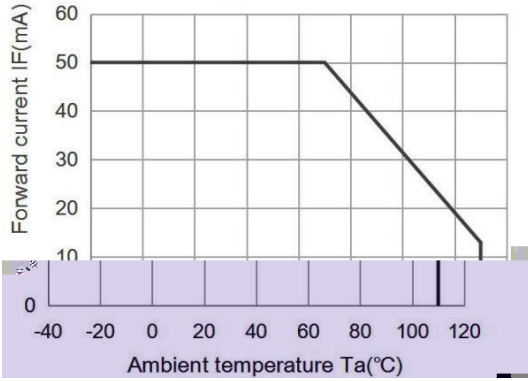


Fig.2 On-state current  $I_{TM}$  (A) vs Ambient temperature

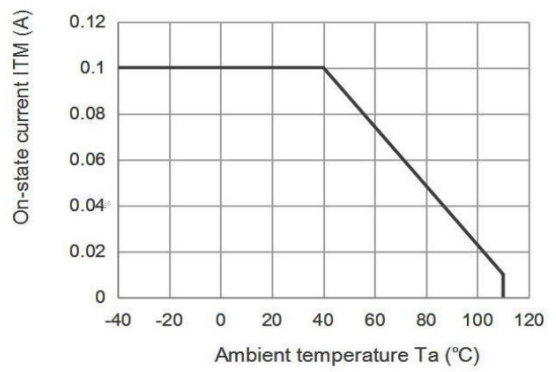


Fig.3 Minimum Trigger Current vs. Ambient temperature

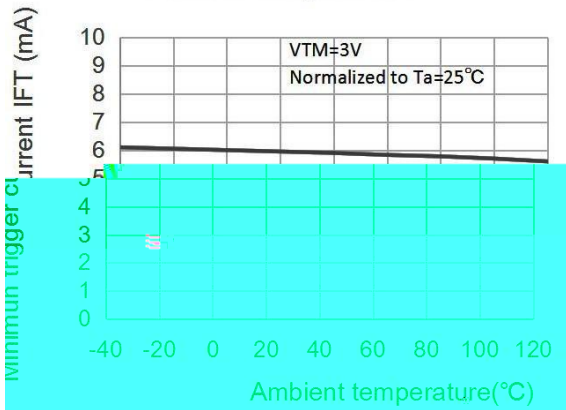


Fig.4 Forward current vs. Forward voltage

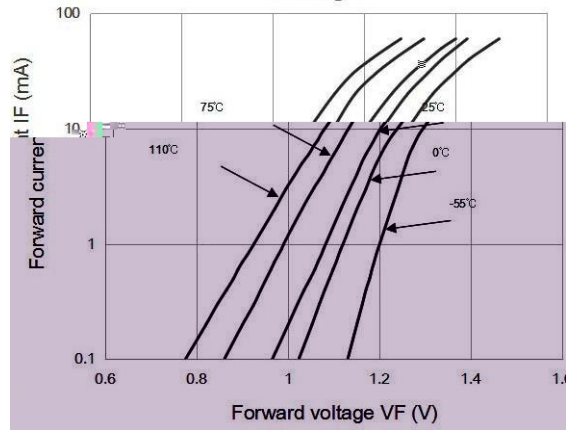


Fig.5 On-state voltage vs. Ambient temperature



Fig.6 Holding current vs. Ambient temperature

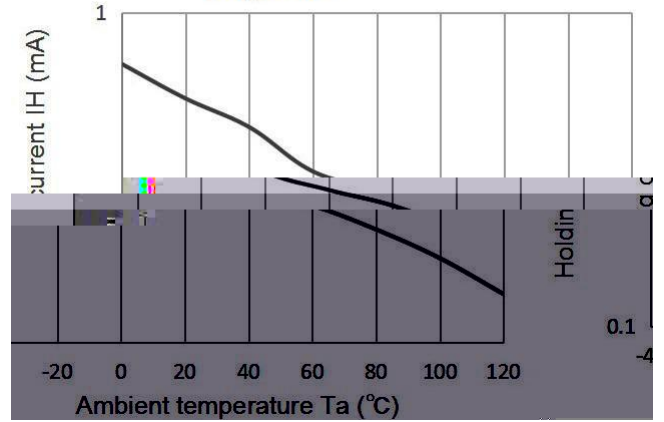


Fig.7 Repetitive peak off-state current vs.  $V_T$

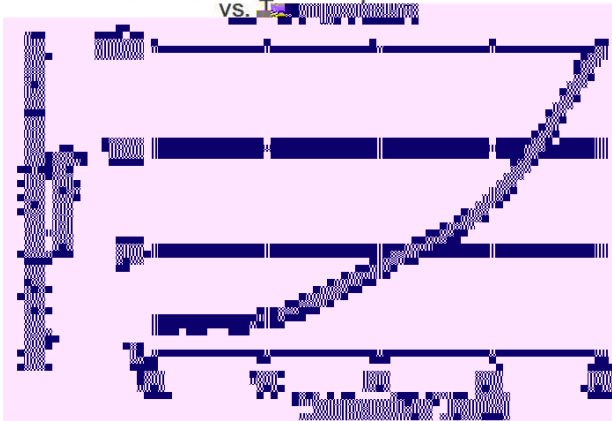
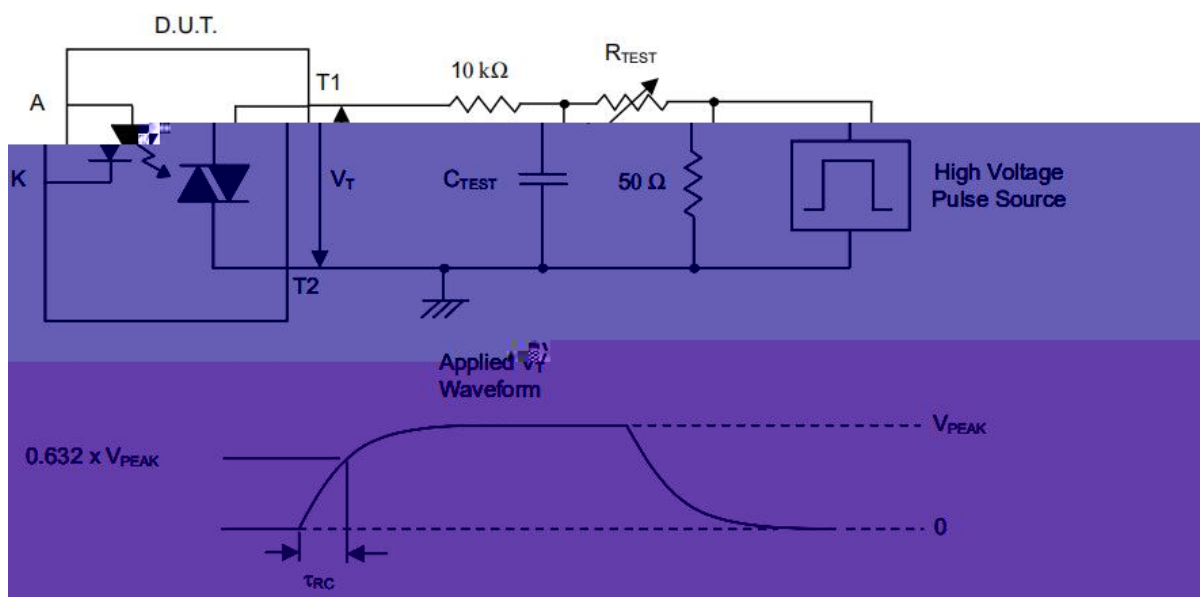
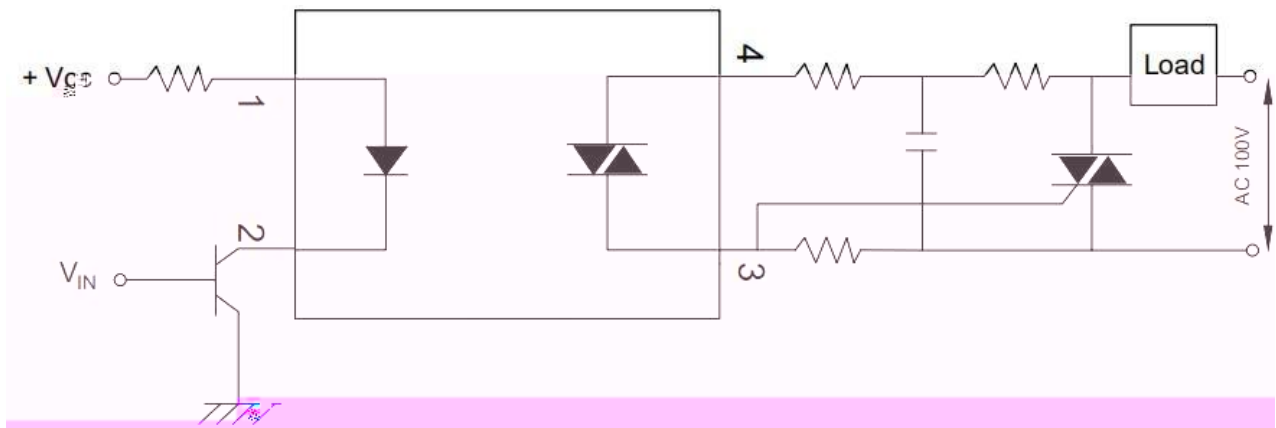
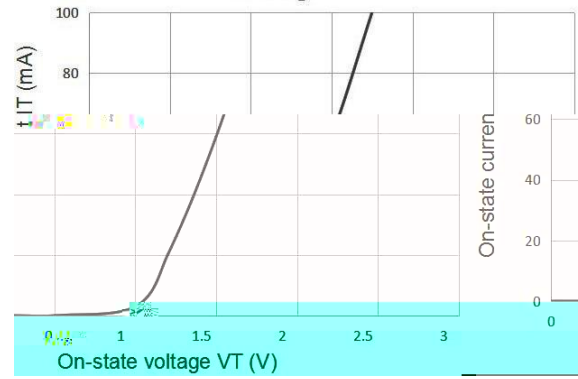


Fig.8 On-state current vs. On-state voltage



## Measurement Method

The high voltage pulse is set to the required  $V_{PEAK}$  value and applied to the D.U.T. output side through the RC circuit above. LED current is not applied. The waveform  $V_T$  is monitored using a x100 scope probe. By varying  $R_{TEST}$ , the  $dv/dt$  (slope) is increased, until the D.U.T. is observed to trigger (waveform collapses). The  $dv/dt$  is then decreased until the D.U.T. stops triggering. At this point,  $\tau_{RC}$  is recorded and the  $dv/dt$  calculated.

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

$$dv/dt = \frac{0.632 \times V_{PEAK}}{\tau_{RC}}$$

For example,  $V_{PEAK} = 600V$  for EL306X series. The  $dv/dt$  value is calculated as follows:

$$dv/dt = \frac{0.63 \times 600}{\tau_{RC}} = \frac{378}{\tau_{RC}}$$